

# N-Channel 100 V (D-S) MOSFET

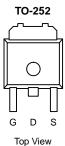
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
	0.055 at V <sub>GS</sub> = 10 V	25				
100	0.057 at V <sub>GS</sub> = 4.5 V	25	21nC			
	0.070 at V <sub>GS</sub> = 2.5 V	18				

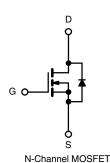
### **FEATURES**

- TrenchFET® power MOSFET
- 100 % UIS tested









PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	100	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20		
	T <sub>C</sub> = 25 °C		25	
Continuous Duois Courset /T 175 °C\	T <sub>C</sub> = 70 °C		20	
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	12 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		10 <sup>b, c</sup>	^
Pulsed Drain Current	I <sub>DM</sub>	80	A	
0 11 0 0 0 1	T <sub>C</sub> = 25 °C		25 <sup>e</sup>	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	6.9 b, c	
Avalanche Current Pulse	l 0.1 mll	I <sub>AS</sub>	33	
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	55	mJ
	T <sub>C</sub> = 25 °C		83	
Marriagona Darray Dispiration	T <sub>C</sub> = 70 °C		58	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	70 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		50 <sup>b, c</sup>	
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum Junction-to-Ambient b, d	t ≤ 10 s	R <sub>thJA</sub>	15	18	°C/W		
Maximum Junction-to-Case	Steady State	$R_{thJC}$	1.5	1.8	-C/W		

#### Notes

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under steady state conditions is 50  $^{\circ}\text{C/W}.$
- e. Calculated based on maximum junction temperature. Package limitation current is 50 A.

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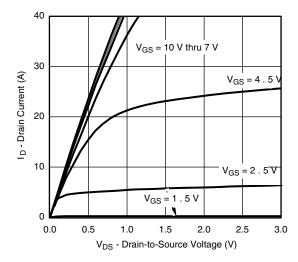
PARAMETER	SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	165	-	m\//°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-11	-	mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.8	1.2	1.6	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zero Gate Voltage Drain Current	leas	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	1		1	μА	
Zero date voltage brain ourient	e Voltage Drain Current $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 \text{ °C}$		-	-	10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	25	-	-	Α	
Drain-Source On-State Resistance a	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_{D=12A}$	-		0.055	Ω	
Drain Course on State Resistance	11DS(on)	$V_{GS}$ =4.5 V, $I_D$ =8A		0.057			
Forward Transconductance a	g <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 12 \text{ A}$	-	25	-	S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		-	-	2300	pF	
Output Capacitance	Coss	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	-	180		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	-	60		
Total Gate Charge	Qg		-	21	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$	-	10	-		
Gate-Drain Charge	Q <sub>gd</sub>		-	9	-		
Gate Resistance	$R_g$	f = 1 MHz	-	1.5	-	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		-	10	15		
Rise Time	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_1 = 5 \Omega$	-	10	15	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10$ Å, $V_{GEN} = 10$ V, $R_g = 1$ $\Omega$	-	15	25		
Fall Time	t <sub>f</sub>		-	10	15		
Drain-Source Body Diode Characteristic	S						
Continuous Source-Drain Diode Current	Is	T <sub>C</sub> = 25 °C	-	-	50		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>		-	-	40	A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 10 A	-	0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	50	75	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	100	150	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	38	-		
Reverse Recovery Rise Time	t <sub>b</sub>	_		12	_	ns	

#### Note

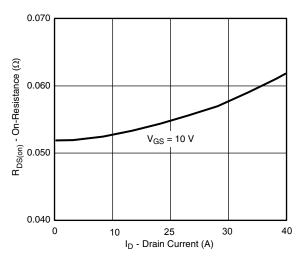
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

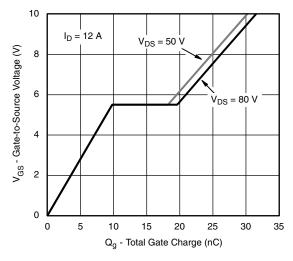




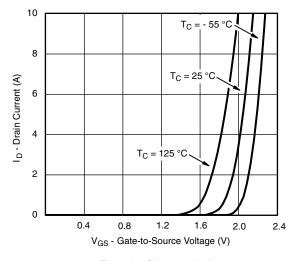




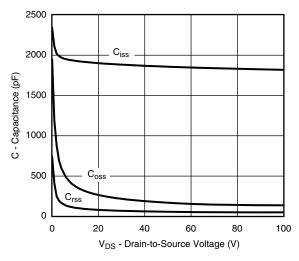
On-Resistance vs. Drain Current



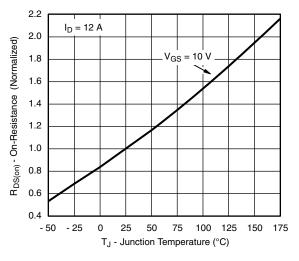
**Gate Charge** 



**Transfer Characteristics** 

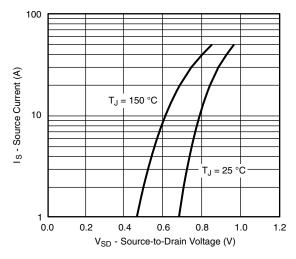


Capacitance

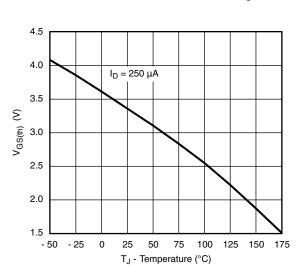


On-Resistance vs. Junction Temperature

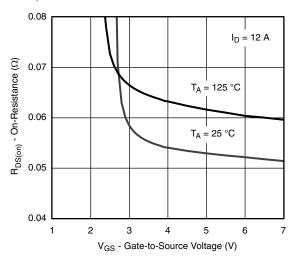




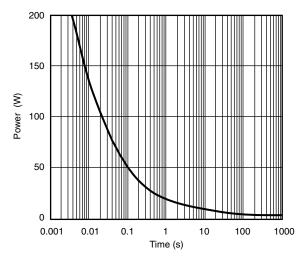
#### Source-Drain Diode Forward Voltage



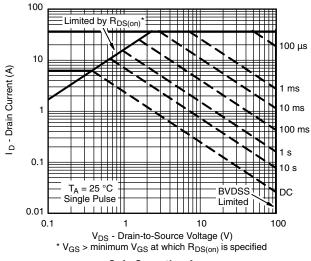
**Threshold Voltage** 



R<sub>DS(on)</sub> vs. V<sub>GS</sub> vs. Temperature

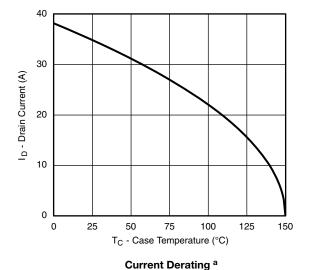


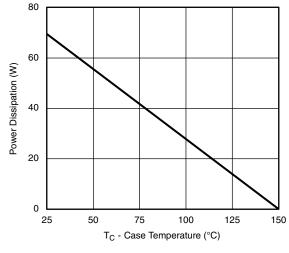
Single Pulse Power, Junction-to-Ambient



Safe Operating Area





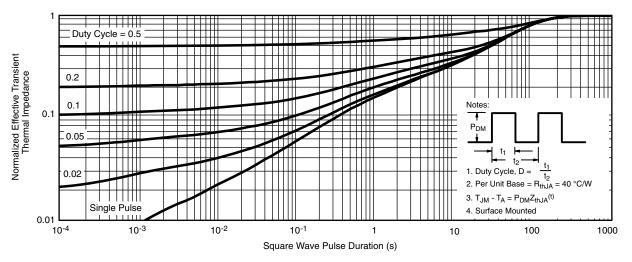


#### **Power Derating**

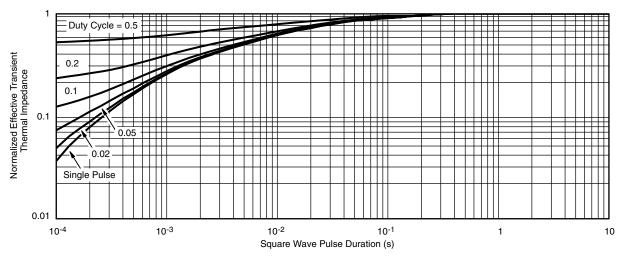
#### Note

a. The power dissipation  $P_D$  is based on  $T_J$  (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





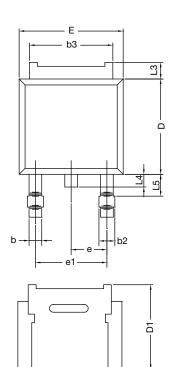
Normalized Thermal Transient Impedance, Junction-to-Ambient

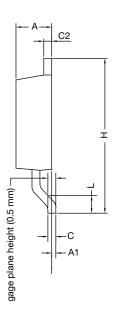


Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA Case Outline**





	MILLIMETERS		INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	4.10	-	0.161	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	2.28 BSC		0.090 BSC		
e1	4.56 BSC		0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.01	1.52	0.040	0.060		
FCN: T16-0236-Rev. P. 16-May-16						

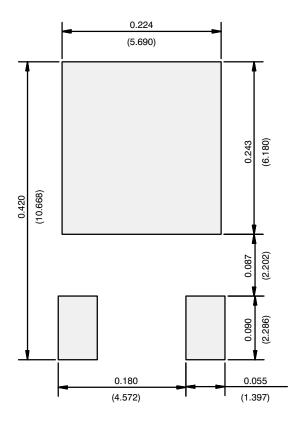
ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347

### Notes

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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